

BEYOND THE LIMITS





Remote Embedded Modular Computers

The new PCI Express over Cable Concept, imagined by ECRIN Systems, will multiplie the capabilities of your next Computer in smaller foot print.

For three decades, Industrial PC's use two key types of architecture inside: ATX/mini-ITX motherboard or PICMG[®] passive backplane. In both cases, the SBC and its I/O cards staid physically linked through Peripheral Component Interconnect PCB - PCI Express promoted by PCI-SIG[®].

myOPALE CONCEPT

myOPALE

myOPALE concept is based on four major principles:

- Broken mechanical link between CPU and I/O cards thanks to PCI Express Over Cable interconnection;
- Building blocks in a standard 5.25" form factor;
- Re-Use of widely deployed interconnect standards from SNIA/SFF Technology Affiliate that encompass cables, connectors, form factor sizes and housing dimensions;
- Thermal solution at building blocks level.

LONG LIFE MANAGEMENT

- Embedded INTEL platforms roadmap exclusive
- 10 years certified longevity
- COM Express design for longevity
- and newer technology
- Revision number control

HIGH PERFORMANCE/WATT

- Quad-Core i7 Gen6 (Skylake) & Gen7 (Kaby Lake)
- 24 x PCIe Gen3 lanes available for external I/O
- NVMe high throughput storage via direct PCI Express interconnect
- Low power consumption with TDP 25 to 45W

SECURITY AND MANAGEMENT

- SEMA Board Controller Agent
- Built in Test with configuration checking
- AMT remote management

COMPUTE DENSITY

- Low Power Modular Blades with I/O's
- Up to 5 Full height I/O cards extension
- in 1U/19'' chassis

TIME TO MARKET

- COTS building blocks ready for immediate system integration services by ECDIN Systems or customer
- by ECRIN Systems or customer • Stock for production
- Cost effectiveness

CUSTOMER KEY BENEFITS





RELIABILITY

- CPU Conduction cooled design
- Extended Temperature option available
- Shocks and vibrations proven
- Redundant system in a unique footprint

HIGH FLEXIBILITY

 Interchangeability for each module CPU or IO thanks standard half-height 5.25"
 Front or rear I/O with easy customised connectors (MIL-38999, XLR, Coax, M12)

myOPALE-CPU

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Module specifications			
module specifications			
		Rear panel	
	G G H	C DE E	
	A & D: Power, Reset buttons, F: USB 3.0 (x4) B & C: SSD, Default LEDs G: Display Port (x2) E: GbE H: Air Inlet / Outlet	A: Power Supply (12V, 5Vstb, PS-ON) D: 3xUSB 2.0, Power, Reset, LEDs, B: 24x PCIe Gen3 link ⁽⁰⁾ , I2C, ext. RTC battery mini-SAS HD (x6) E: SATA 6.0 Gb/s (x2) C: Air Outlet / Inlet (1) PCIe configuration support 8/8/4/4 or 8/4/4/4/	
Construction	Arti correction and long term heavy duty steel black color		
	Anti-contosion and long termineary outry steet, black color		
Dimensions (w x n x D) Weight			
Cooling	1.43 Ky Cold plate with Duch Pull forced air cooled - Two 40mm hall bearing fanc with monitoring		
Cooling Dower Supply	ATX mode : +12V and 5Veth		
Power Suppry	AT model: +I2V and 5vstp		
Drivo Pav	Al mode : +IZV ONIY		
Carton Size (W x H x D)	Internal drive bay lor 2.5 SATA 6.0 GD/S SSD		
Processor specifications	Skylake Kaby lake		
COM module	СОМе 3.0 Туре 6		
Processor	6 th Gen Intel [®] Core [™] , Intel [®] Xeon [®] E3-1500 v5 Processor	7 th Gen Intel [®] Core [™] , Intel [®] Xeon [®] E3-1500 v6 Processor	
Chipset	CM236 (supports ECC memory, Intel® AMT)	CM238 (supports ECC memory, Intel AMT)	
	QM170 (supports non-ECC, Intel® AMT)	QM175 (supports non-ECC, Intel AMT)	
Memory	Dual channel 1867/2133 MHz DDR4 32GB max. 2xSODIMM	Dual channel 2133/2400 MHz DDR4 32GB max. 2xSODIMM	
	(ECC/non-ECC support dependent on selected CPU/PCH)	(ECC/non-ECC support dependent on selected CPU/PCH)	
Video	Intel [®] Generation 9 LP Graphics Core, Hardware encode/transcode HD content (including HEVC)		
Eth a sec al.	2X DISPIBYPORTS		
Ethernet	1x GDE (12/9LM with AMI 11.0 support)		
UISK	3X SATA 6.0 GD/S POFIS		
0.20	4X USB 3.0 (Holli pallel)		
TDM	SX USD 2.0 (Tedi Jaliel) Chinest Atmol AT075C2204 - TDM 12/2.0	Chinest: Infineer - TDM 2.0	
Hardware Monitor	CHIPSEL ALIHEL AL97 SUS204 - TFM 1.2/2.0 SEMA® Reard Management Controllor: voltage/current monitoring, power segue	Chipsel, hillieon - Irm 2.0	
	logistics and forensic information, general nurnose I2C failsafe BIOS (dual BIO)	S) watchdog timer and fan control	
Environmental specifications			
Temperature	Operating : -10° ~ +55°C (*) / Storage -40° ~ +85°C (*) extended temperature on reques	t	
Humidity	Operating 1 to 1956 of the 195		
Altitude	0-3000m (0-10 000ft) operating		
Shocks (with SSD)	Operating: 25G @ 11ms / 20G @ 20ms - 6 axis (MIL STD 810 G. method. 516.6)		
Vibration (with SSD)	Operating: 5~7Hz / 10mm, 10~2000Hz / 2G - 3 axis, 2 sweeps, 15min (MIL STD 810 G. method. 514.6)		
CE Certification	EMC: 2014/30 / ELI		
	SAFETY: 2014/35/UE		
Software			
System Monitorina	Intel® AMT for remote management		
and management	SEMA® Board Controller		
, , , , , , , , , , , , , , , , , , ,	Built In Test ECRIN (Power-on BIT with Configuration checking, Continuous BIT,	Maintenance BIT)	
Operating System	Windows 10/8.1 64-bit, Windows 7 32/64-bit,	Windows 10 64-bit, Windows 10 IOT Enterprise 64-bit,	
	Linux 64-bit	Linux 64-bit, VxWorks	
	Skylake	Kaby lake	
Xeon E5-1500 v5 / v6	Xeon® E3-1515M v5 2.8~3.7GHz, 8MB, 45W (4C/8T, GT4e)	Xeon® E3-1505M v6 3.0/4.0GHz (Turbo), 45W (4C/8T, GT2)	
- Chipset CM236 / CM238	Xeon® E3-1505M v5 2.8~3.7GHz, 8MB, 45W (4C/8T, GT2)	Xeon® E3-1505L v6 2.2/3.0GHz (Turbo), 25W (4C/8T. GT2)	
- ECC memory support	Xeon® E3-1505L v5 2.0~2.8GHz, 8MB, 25W (4C/8T. GT2)		
Intel [®] Core™ Gen6 / Gen7	Core™ i7-6820EQ 2.8~3.5GHz. 8MB. 45W (4C/8T. GT2)	Core™ i7-7820EQ 3.0~3.7GHz. 8MB. 45W (4C/8T. GT2)	
- Chipset QM170 / QM175	Core™ i7-6822EQ 2.0~2.8GHz, 8MB, 25W (4C/8T. GT2)	Core™ i5-7440EQ 2.9~3.6GHz, 6MB , 45W (4C/4T. GT2)	
- non-ECC memory support	Core™ i5-6440EQ 2.7~3.4GHz, 6MB, 45W (4C/4T, GT2)	Core™ i5-7442EQ 2.1~2.9GHz, 6MB, 25W (4C/4T, GT2)	
,,	Core™ i5-6442EQ 1.9~2.7GHz, 6MB, 25W (4C/4T, GT2)	Core™ i3-7100E 2.9GHz, 3MB, 35W (2C/4T. GT2)	
	Core™ i3-6100E 2.7GHz, 3MB, 35W (2C/4T. GT2)	Core™i3-7102E 2.1GHz, 3MB. 25W (2C/4T. GT2)	
	Core™ i3-6102E 1.9GHz, 3MB, 25W (2C/4T, GT2)		

myOPALE-10

Module specifications			
	A: 8x PCle Gen3 link ⁽²⁾ , mini-SAS HD (x2) B: 3x wires fan connectors (x2) C: PCle x4 slot (x16 mechanical) or N/A D: PCle x4 or PCle x8 slot (x16 mechanical) (2) PCle configuration support 8/0 or 4/4	General Font panel General Genera	
Construction	Anti-corrosion and long term heavy-duty steel, black color		
Dimensions (W x H x D)	5.25 " with 7.9 inch depth (146x42x200mm)		
Weight	0.5 kg		
Card lock	Holding part for full height and low profile PCIe board		
Power Supply	+12V only		
Front panel	2x full height PCIe board		
Rear panel	8x PCIe Gen3 link on 2x mini-SAS HD		
Carton Size (W x H x D)	220x120x270 mm		
Backplane specifications			
I/O expansion	Version 1: 2x PCle x4 slots (PCle x16 connector) Version 2: 1x PCle x8 slot (PCle x16 connector) Support half size and full length PCle card		
Power Supply	12V to 3.3V DC converter Remote control from myOPALE-CPU module (through mini-SAS HD Sideband)		
Fan control	3-wire fans (x2) On board and remote temperature sensors Programmable Look Up Table for temperature / fan speed monitoring Remote control from myOPALE-CPU module (through mini-SAS HD Sideband) WAKE signal to myOPALE-CPU module (through mini-SAS HD Sideband)		
Environmental specifications	אאוגב זוקוומו נט ווויזטראבב טרט וווטעעופ (נוווטעקוו וווווו־אאז חט זועפטלווע)		
Tomporaturo	Operating: 10° ~ +55°C (*) / Storage 40° ~ +05°C (*)		
Humidity	Operating : 5 to 00% pap conducing		
CE Cortification	operating . 5 to 50% non-condensing		
	EMUL 2014/30 / EU CAFETV: 2014/2E/UF		
Suctom Monitoring and monor	SAFELT. 2014/30/0E		
System Monitoring and manag	Demote neuror temporature and fan manifesing fram muODALE ODL se duit		
	Remote nower remperature and ran monitoring from myuPALE-CPU module		



myOPALE Use Cases

myOPALE provides a simple method for extended applications that need more I/O boards than were fitted in a standard Industrial PC based on backplane PCB. Here are some application examples where myOPALE concept is demonstrated as a major differentiator from the legacy Industrial PC's.



Audio Music, NVIDIA Gamer, Broadcast, Info-Comm, Network...

PCIe x4 to mini-SAS HD converter M.2 to mini-SAS HD converter

YOUR LEADING TRUSTED PARTNER FOR EMBEDDED

ECRIN Systems is both Manufacturer and System Integrator

MANUFACTURER, we became in 2007

- Thanks to the proximity and great commitment we develop with our leading trusted customers and huge experience acquired in embedded market since 1976, our marketing department knows what you will need in terms of systems and services for the next five years. At ECRIN Systems, we innovate and create the disruptive technology and products that will carry your project up to the success with complete satisfaction.
- Always driven by flexibility, long life and re-use principles, all our COTS System platforms are modular, based on embedded open standards driven by PICMG[®], PCI-SIG[®] and VITA[®] normalization comities, to be easily configured, modified and customized according to your unique and specific requirements with SWaP constraints into industrial environments.
- myOPALE is a new demonstration of our DNA, thanks this new generation of ready to use building blocks that nobody imagined before our R&D engineers done it.

SYSTEM INTEGRATOR, we are since 40 years

- With 70% of our business driven by project to develop Computer-on-Demand, we re-use our proven COTS System building blocks and IPs to reduce your time to market, manage the risk during development phase and reduce your non-recurrent cost. Dedicated Project Manager with Project Quality Engineer will assist you all along the program. With myOPALE new infrastructure, we are able to develop and build SWaP high density systems that was not doable until now in such Small Form Factor.
- If myOPALE concept makes sense for you, do not hesitate to contact us. We will provide your complete integrated computer with Environmental Qualification Tests passed and mandatory Certification stickers for domestic and export countries.



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